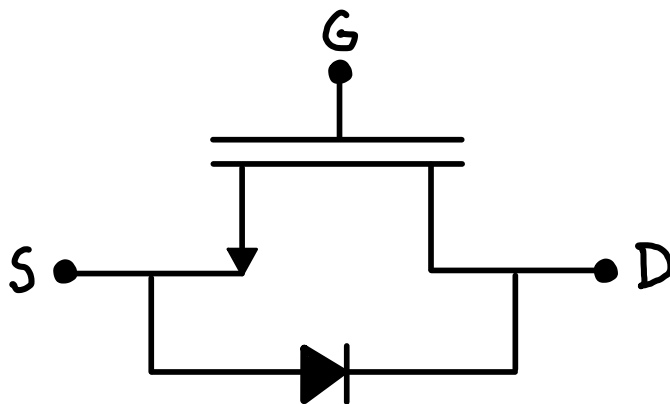
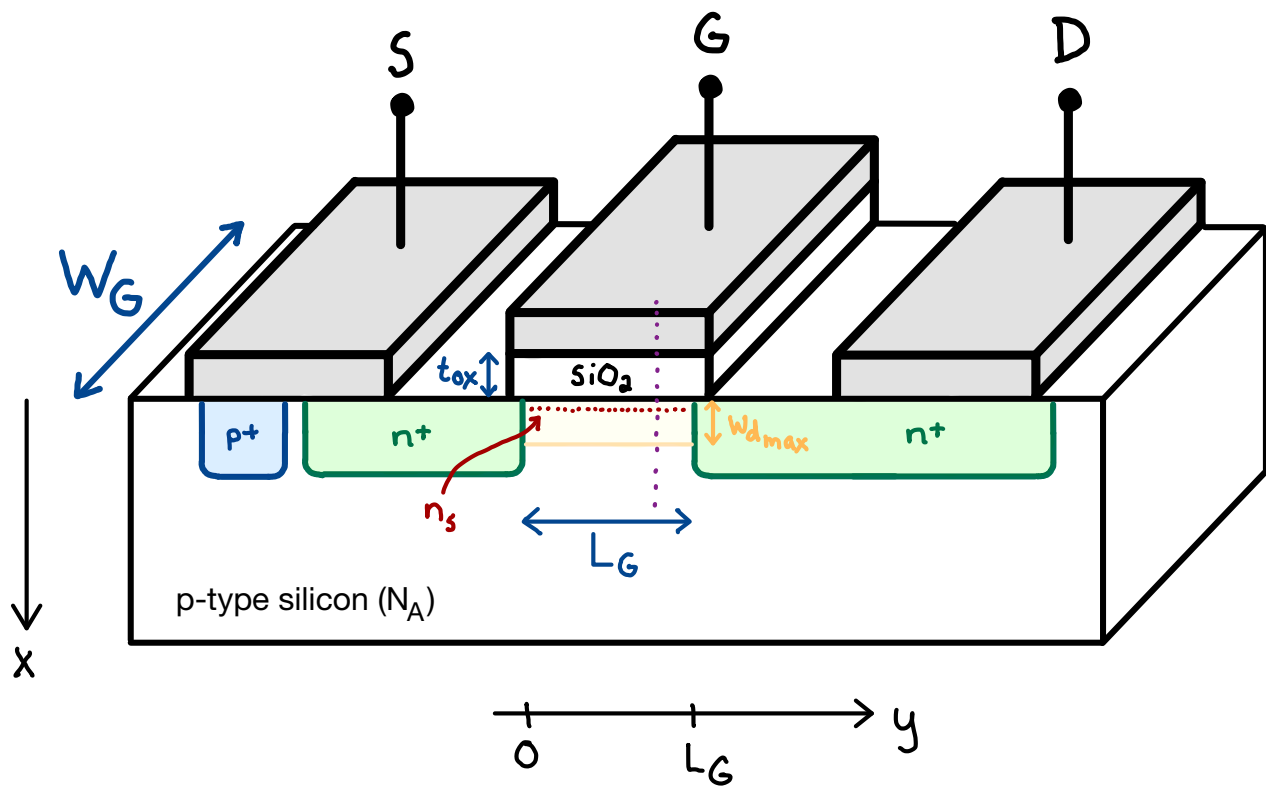
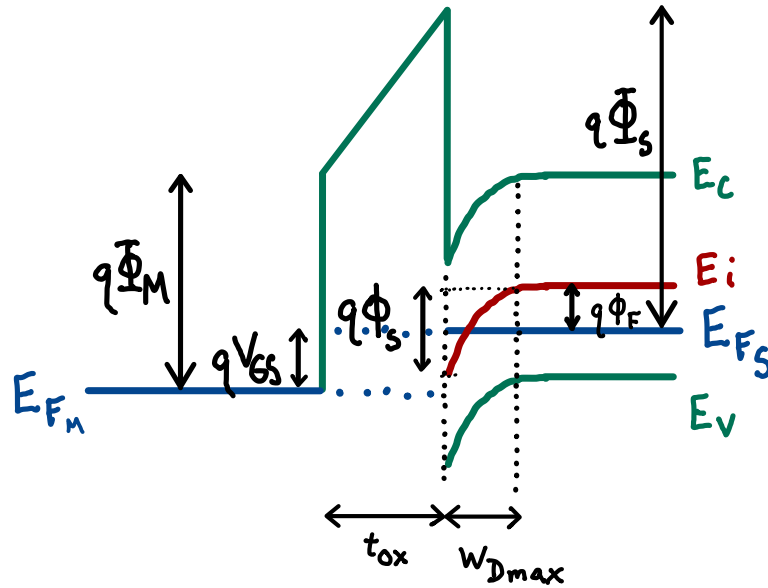


MOSFETs



Band diagram along purple dotted line ($V_{GS} \geq V_{Th}$):



$$\Phi_{MS} = \Phi_M - \Phi_S$$

$$\phi_F = \frac{kT}{q} \ln\left(\frac{N_A}{n_i}\right)$$

$$\phi_s = 2\phi_F \quad (\text{condition for strong inversion})$$

$$W_{Dmax} = 2\sqrt{\frac{\epsilon_s \phi_F}{q N_A}}$$

$$V_{FB} = \Phi_{MS} - \frac{Q_i}{C_{ox}}$$

$Q_i \equiv$ interface charge

$$C_{ox} = \frac{\epsilon_i}{t_{ox}}$$

$$V_{Th} = \Phi_{MS} - \frac{Q_i}{C_{ox}} - \frac{Q_d}{C_{ox}} + 2\phi_F \quad Q_d = -q N_A W_{Dmax}$$

$$\underbrace{\phantom{<0}}_{<0} \quad \underbrace{\phantom{<0}}_{<0} \quad \underbrace{}_{>0} \quad \underbrace{}_{>0}$$

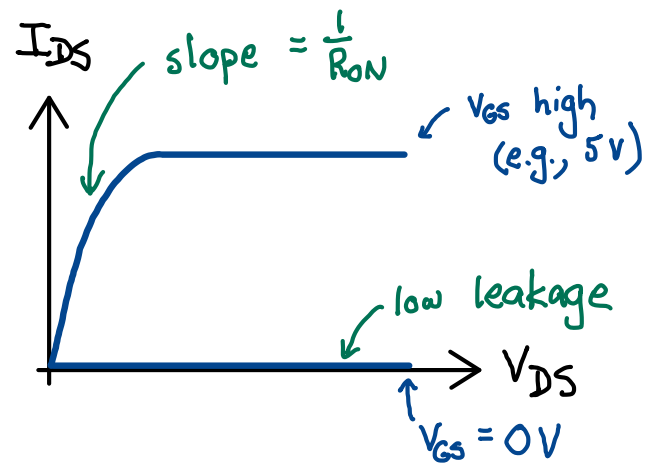
Materials for source/drain and gate contacts:

	<u>Al</u>	<u>n⁺-poly</u>	<u>Tungsten (W)</u>	<u>p⁺-poly</u>
$q\Phi_M(\text{eV})$	4.1	4.05	4.61	5.17
	<u>s/d</u>		<u>Gate</u>	

. p⁺-poly gate can be deposited by CVD at same time as gate oxide

Desirable characteristics for MOSFETs:

- $V_{Th} \sim 1.5V-2V$
- Fast switching speeds
- Low switching loss (small R_{on})
- Low conductive power loss (low leakage)
- Large density of devices

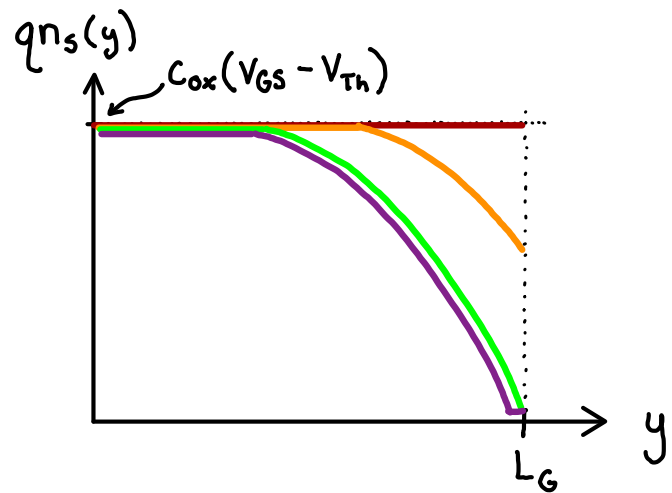
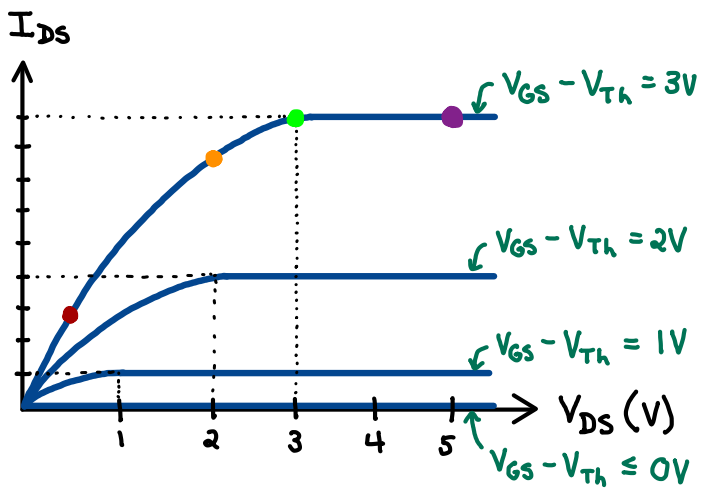


- L_G small (Moore's Law)
- Constant field scaling (scale C_{ox} with L_G)

MOSFET I-V Characteristics

- Long channel device ($L_G \approx 2 \mu m$)
- Short channel device ($L_G \approx 0.2 \mu m$)

Long Channel MOSFET:



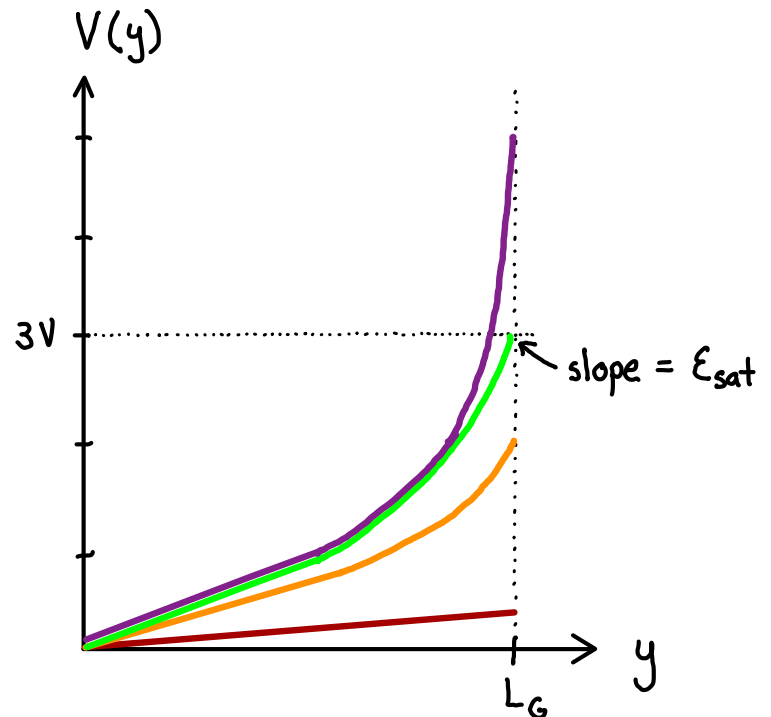
$$V_{knee} = V_{Dsat} = V_{GS} - V_{Th}$$

$$I_{Dsat} = \frac{\mu_n C_{ox} W_G}{2L_G} (V_{GS} - V_{Th})^2$$

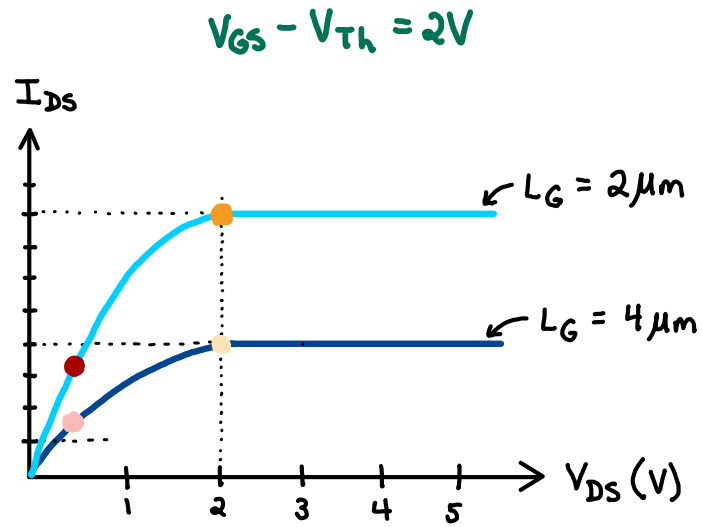
$$E_y(y) = \frac{dV(y)}{dy}$$

$$v_{el}(y) = \mu_n E_y(y)$$

$$I_{DS} \propto n_s(y) \cdot v_{el}(y)$$



Scaling of Long Channel MOSFETs



(Note: only the gate length is varied)

